

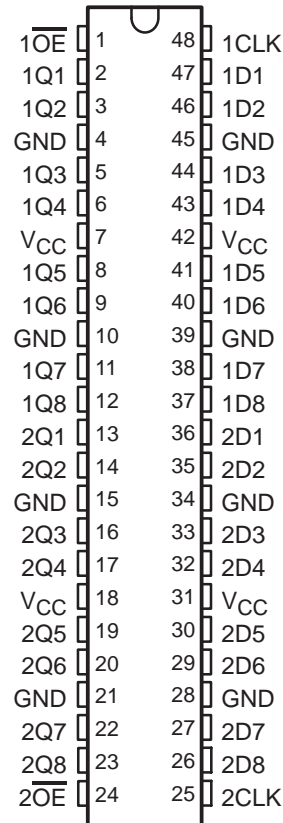
# SN74LVC16374A

## 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS663D – MARCH 2001 – REVISED AUGUST 2003

- Member of the Texas Instruments Widebus™ Family
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<0.8\text{ V}$  at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  $>2\text{ V}$  at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input and Output Voltages With 3.3-V  $V_{CC}$ )
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

DGG, DGV, OR DL PACKAGE  
(TOP VIEW)



### description/ordering information

This 16-bit edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74LVC16374A is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. The device can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

### ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP – DL	Tube	SN74LVC16374ADL	LVC16374A
		Tape and reel	SN74LVC16374ADLR	
	TSSOP – DGG	Tape and reel	SN74LVC16374ADGGR	LVC16374A
	TVSOP – DGV	Tape and reel	SN74LVC16374ADGVR	LD374A
	VFBGA – GQL	Tape and reel	SN74LVC16374AGQLR	LD374A
VFBGA – ZQL (Pb-free)	SN74LVC16374AZQLR			

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2003, Texas Instruments Incorporated

# SN74LVC16374A

## 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS663D – MARCH 2001 – REVISED AUGUST 2003

### description/ordering information

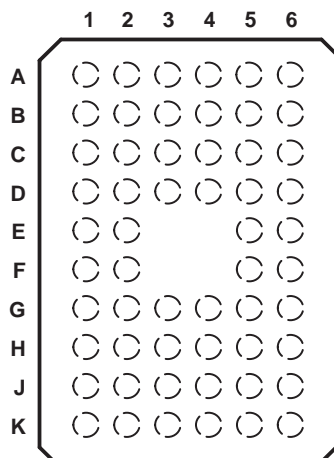
$\overline{OE}$  does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

GQL OR ZQL PACKAGE  
(TOP VIEW)



### terminal assignments

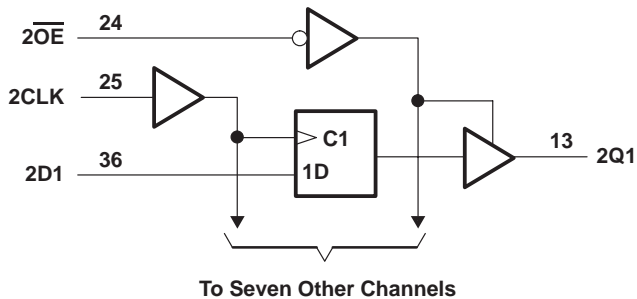
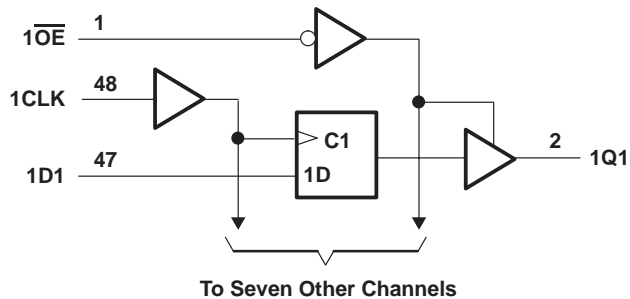
	1	2	3	4	5	6
A	$\overline{1OE}$	NC	NC	NC	NC	1CLK
B	1Q2	1Q1	GND	GND	1D1	1D2
C	1Q4	1Q3	$V_{CC}$	$V_{CC}$	1D3	1D4
D	1Q6	1Q5	GND	GND	1D5	1D6
E	1Q8	1Q7			1D7	1D8
F	2Q1	2Q2			2D2	2D1
G	2Q3	2Q4	GND	GND	2D4	2D3
H	2Q5	2Q6	$V_{CC}$	$V_{CC}$	2D6	2D5
J	2Q7	2Q8	GND	GND	2D8	2D7
K	$\overline{2OE}$	NC	NC	NC	NC	2CLK

NC – No internal connection

FUNCTION TABLE  
(each flip-flop)

$\overline{OE}$	INPUTS		OUTPUT Q
	CLK	D	
L	$\uparrow$	H	H
L	$\uparrow$	L	L
L	H or L	X	$Q_0$
H	X	X	Z

### logic diagram (positive logic)



Pin numbers shown are for the DGG, DGV, and DL packages.

# SN74LVC16374A

## 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS663D – MARCH 2001 – REVISED AUGUST 2003

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 6.5 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1) .....	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, $V_O$ (see Notes 1 and 2) .....	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ ) .....	–50 mA
Continuous output current, $I_O$ .....	±50 mA
Continuous current through each $V_{CC}$ or GND .....	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): DGG package .....	70°C/W
DGV package .....	58°C/W
DL package .....	63°C/W
GQL/ZQL package .....	42°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The value of  $V_{CC}$  is provided in the recommended operating conditions table.  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
$V_{CC}$ Supply voltage	Operating	1.65	3.6	V
	Data retention only	1.5		
$V_{IH}$ High-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_{CC}$		V
	$V_{CC} = 2.3$ V to 2.7 V	1.7		
	$V_{CC} = 2.7$ V to 3.6 V	2		
$V_{IL}$ Low-level input voltage	$V_{CC} = 1.65$ V to 1.95 V		$0.35 \times V_{CC}$	V
	$V_{CC} = 2.3$ V to 2.7 V		0.7	
	$V_{CC} = 2.7$ V to 3.6 V		0.8	
$V_I$ Input voltage		0	5.5	V
$V_O$ Output voltage	High or low state	0	$V_{CC}$	V
	3-state	0	5.5	
$I_{OH}$ High-level output current	$V_{CC} = 1.65$ V		–4	mA
	$V_{CC} = 2.3$ V		–8	
	$V_{CC} = 2.7$ V		–12	
	$V_{CC} = 3$ V		–24	
$I_{OL}$ Low-level output current	$V_{CC} = 1.65$ V		4	mA
	$V_{CC} = 2.3$ V		8	
	$V_{CC} = 2.7$ V		12	
	$V_{CC} = 3$ V		24	
$\Delta t/\Delta v$ Input transition rise or fall rate			10	ns/V
$T_A$ Operating free-air temperature		–40	85	°C

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN74LVC16374A

## 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS663D – MARCH 2001 – REVISED AUGUST 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> -0.2			V
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			
	I <sub>OH</sub> = -8 mA	2.3 V	1.7			
	I <sub>OH</sub> = -12 mA	2.7 V	2.2			
	I <sub>OH</sub> = -24 mA	3 V	2.4			
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2	V
	I <sub>OL</sub> = 4 mA	1.65 V			0.45	
	I <sub>OL</sub> = 8 mA	2.3 V			0.7	
	I <sub>OL</sub> = 12 mA	2.7 V			0.4	
	I <sub>OL</sub> = 24 mA	3 V			0.55	
I <sub>I</sub>	V <sub>I</sub> = 0 to 5.5 V	3.6 V			±5	μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0			±10	μA
I <sub>OZ</sub>	V <sub>O</sub> = 0 to 5.5 V	3.6 V			±10	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	I <sub>O</sub> = 0		20	μA
	3.6 V ≤ V <sub>I</sub> ≤ 5.5 V‡				20	
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V			5	pF
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V			6.5	pF

† All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

‡ This applies in the disabled state only.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	150		150		150		150		MHz
t <sub>w</sub>	Pulse duration, CLK high or low	3.3		3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time, data before CLK↑	2.4		1.6		1.9		1.9		ns
t <sub>h</sub>	Hold time, data after CLK↑	0.8		1		1.1		1.9		ns

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			150		150		150		150		MHz
t <sub>pd</sub>	CLK	Q	1	6.5	1	4.3	1	4.9	1.5	4.5	ns
t <sub>en</sub>	$\overline{OE}$	Q	1	6.7	1	4.7	1	5.3	1.5	4.6	ns
t <sub>dis</sub>	$\overline{OE}$	Q	1	10.7	1	5	1	6.1	1.5	5.5	ns
t <sub>sk(o)</sub>									1		ns



**SN74LVC16374A**  
**16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP**  
**WITH 3-STATE OUTPUTS**

SCAS663D – MARCH 2001 – REVISED AUGUST 2003

operating characteristics,  $T_A = 25^\circ\text{C}$

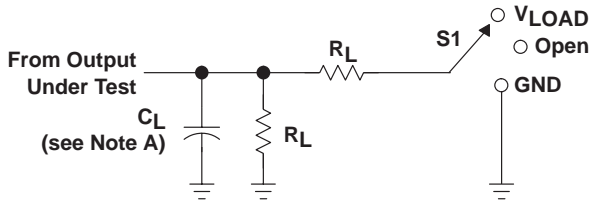
PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT	
			TYP	TYP	TYP		
C <sub>pd</sub>	Power dissipation capacitance per flip-flop	Outputs enabled	f = 10 MHz	47	52	58	pF
		Outputs disabled		21	23	24	

# SN74LVC16374A

## 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS663D – MARCH 2001 – REVISED AUGUST 2003

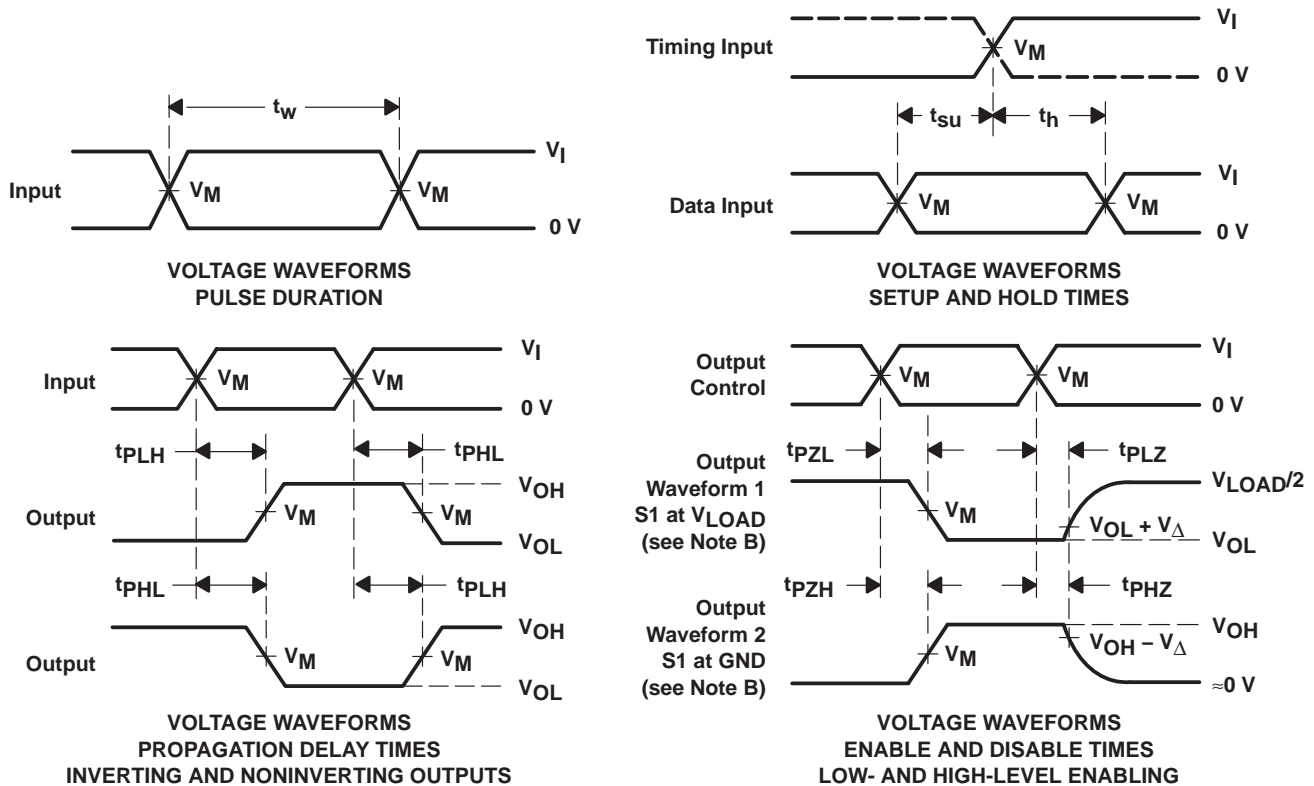
### PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	VLOAD
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V

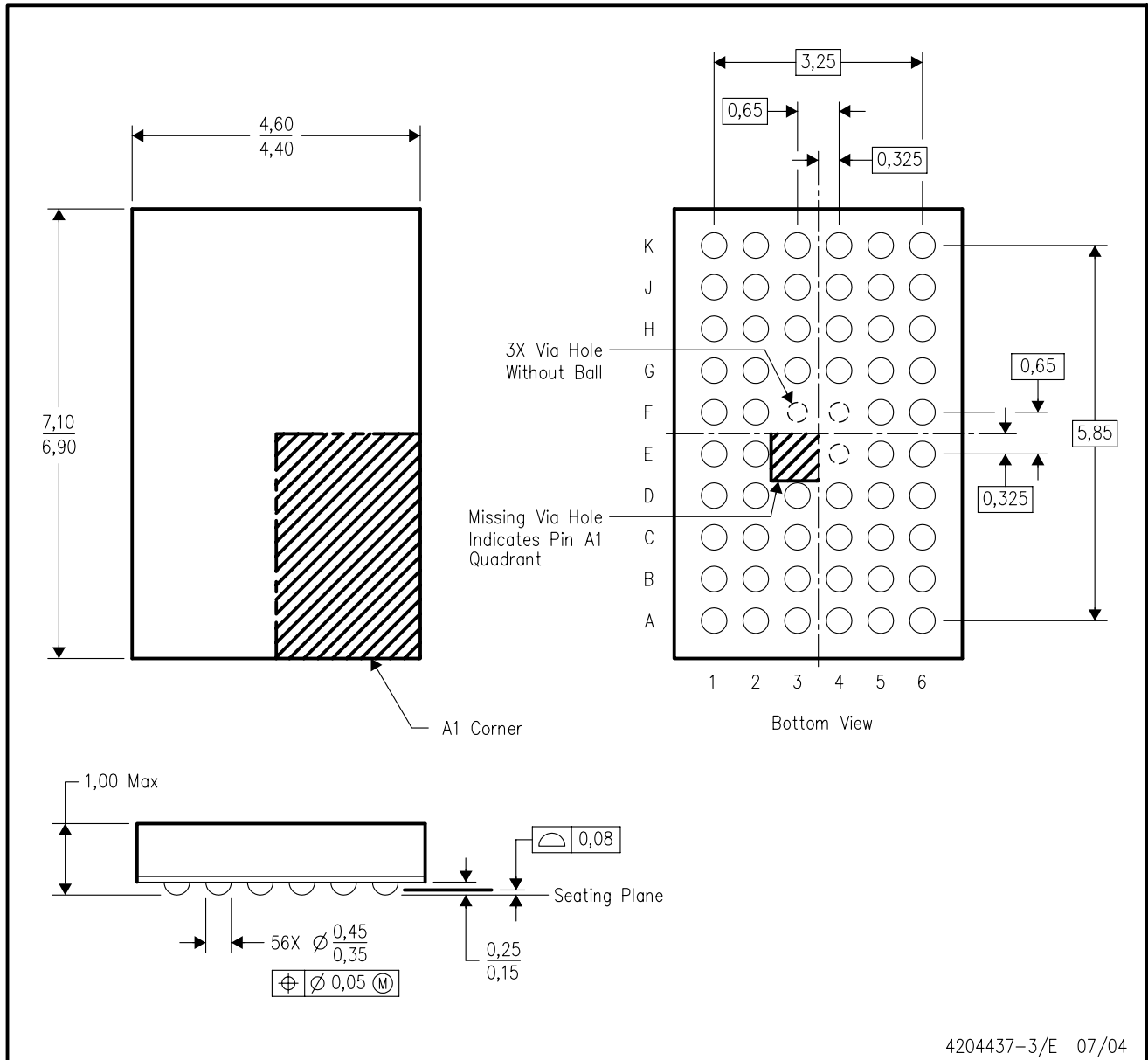


- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ .
  - The outputs are measured one at a time with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BA.
  - D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

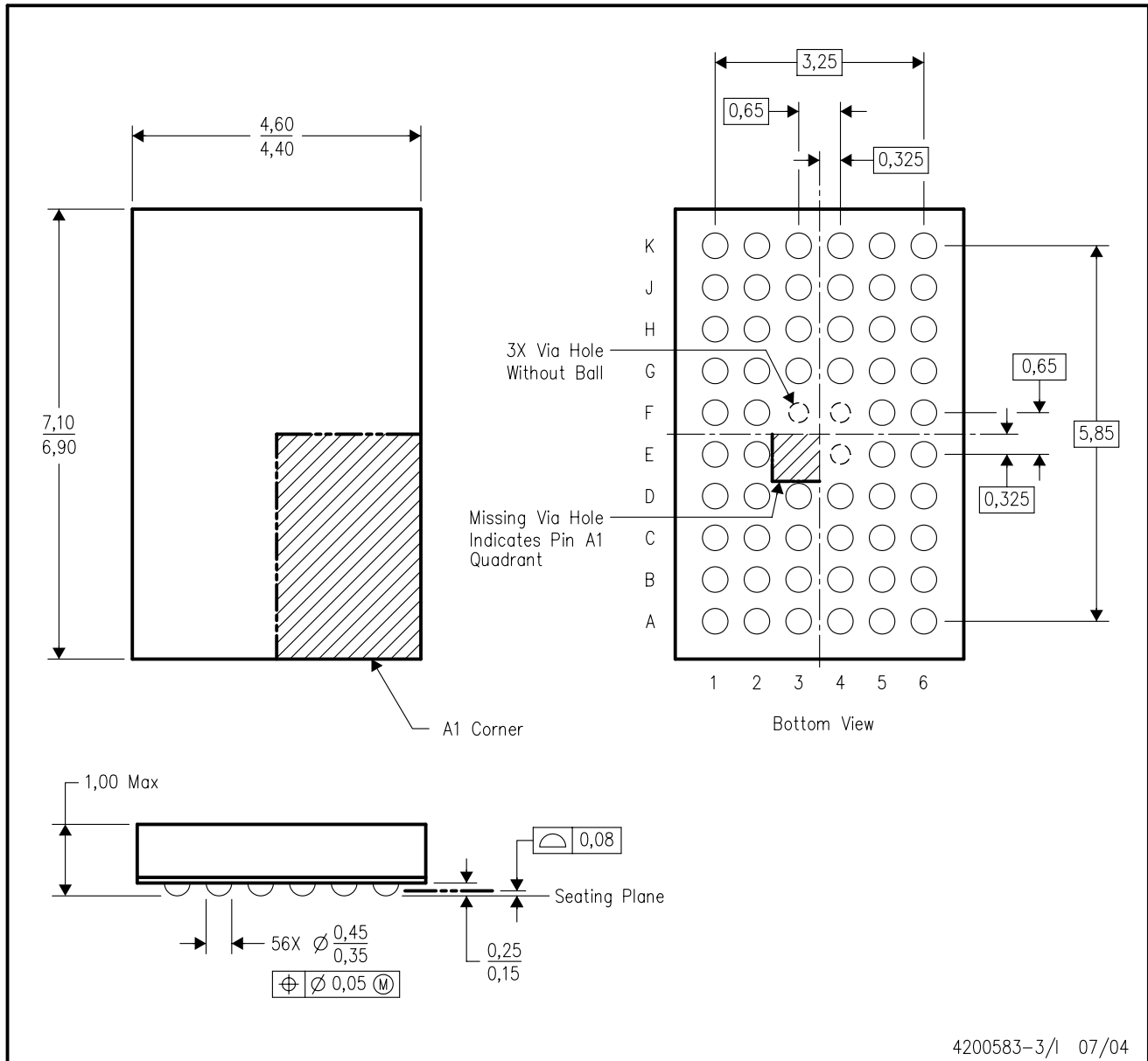


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BA.
  - D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

DL (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<b>Products</b>		<b>Applications</b>	
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
		Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
		Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments  
Post Office Box 655303 Dallas, Texas 75265